

Global 3D-IC Packaging Market 2025 by Company, Regions, Type and Application, Forecast to 2031

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Abstracts

According to our (Global Info Research) latest study, the global 3D-IC Packaging market size was valued at US\$ 19010 million in 2024 and is forecast to a readjusted size of USD 30430 million by 2031 with a CAGR of 7.0% during review period.

3D-IC (Three-Dimensional Integrated Circuit) packaging is an advanced packaging technology used in the semiconductor industry to vertically stack multiple integrated circuit (IC) dies or chips. It involves stacking and interconnecting multiple IC chips within a single package, allowing for increased integration, improved performance, and reduced form factor of electronic devices.

The global market for semiconductor was estimated at US\$ 579 billion in the year 2022, is projected to US\$ 790 billion by 2029, growing at a CAGR of 6% during the forecast period. Although some major categories are still double-digit year-over-year growth in 2022, led by Analog with 20.76%, Sensor with 16.31%, and Logic with 14.46% growth, Memory declined with 12.64% year over year. The microprocessor (MPU) and microcontroller (MCU) segments will experience stagnant growth due to weak shipments and investment in notebooks, computers, and standard desktops. In the current market scenario, the growing popularity of IoT-based electronics is stimulating the need for powerful processors and controllers. Hybrid MPUs and MCUs provide real-time embedded processing and control for the topmost IoT-based applications, resulting in significant market growth. The Analog IC segment is expected to grow gradually, while demand from the networking and communications industries is limited. Few of the emerging trends in the growing demand for Analog integrated circuits include signal conversion, automotive-specific Analog applications, and power management. They drive the growing demand for discrete power devices.

This report is a detailed and comprehensive analysis for global 3D-IC Packaging market. Both quantitative and qualitative analyses are presented by company, by region & country, by Type and by Application. As the market is constantly changing, this report explores the competition, supply and demand trends, as well as key factors that contribute to its changing demands across many markets. Company profiles and product examples of selected competitors, along with market share estimates of some of the selected leaders for the year 2025, are provided.

Key Features:

Global 3D-IC Packaging market size and forecasts, in consumption value (\$ Million), 2020-2031

Global 3D-IC Packaging market size and forecasts by region and country, in consumption value (\$ Million), 2020-2031

Global 3D-IC Packaging market size and forecasts, by Type and by Application, in consumption value (\$ Million), 2020-2031

Global 3D-IC Packaging market shares of main players, in revenue (\$ Million), 2020-2025

The Primary Objectives in This Report Are:

- To determine the size of the total market opportunity of global and key countries
- To assess the growth potential for 3D-IC Packaging
- To forecast future growth in each product and end-use market
- To forecast future factors affecting the marketplace

This report profiles key players in the global 3D-IC Packaging market based on the following parameters - company overview, revenue, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include Synopsys, Cadence, XMC, United Microelectronics Corp, TSMC, SPIL, STMicroelectronics, ASE Group, Amkor Technology, Intel Corporation, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Market segmentation

3D-IC Packaging market is split by Type and by Application. For the period 2020-2031, the growth among segments provides accurate calculations and forecasts for Consumption Value by Type and by Application. This analysis can help you expand your business by targeting qualified niche markets.

Market segment by Type

TSV

TGV

Silicon Interposer

Market segment by Application

Consumer Electronics

Medical Devices

Automotive

Others

Market segment by players, this report covers

Synopsys

Cadence

XMC

United Microelectronics Corp

TSMC

SPIL

STMicroelectronics

ASE Group

Amkor Technology

Intel Corporation

GlobalFoundries

Invensas

Toshiba Corporation

Micron Technology

Xilinx

Market segment by regions, regional analysis covers

North America (United States, Canada and Mexico)

Europe (Germany, France, UK, Russia, Italy and Rest of Europe)

Asia-Pacific (China, Japan, South Korea, India, Southeast Asia and Rest of Asia-Pacific)

South America (Brazil, Rest of South America)

Middle East & Africa (Turkey, Saudi Arabia, UAE, Rest of Middle East & Africa)

The content of the study subjects, includes a total of 13 chapters:

Chapter 1, to describe 3D-IC Packaging product scope, market overview, market estimation caveats and base year.

Chapter 2, to profile the top players of 3D-IC Packaging, with revenue, gross margin, and global market share of 3D-IC Packaging from 2020 to 2025.

Chapter 3, the 3D-IC Packaging competitive situation, revenue, and global market share of top players are analyzed emphatically by landscape contrast.

Chapter 4 and 5, to segment the market size by Type and by Application, with consumption value and growth rate by Type, by Application, from 2020 to 2031

Chapter 6, 7, 8, 9, and 10, to break the market size data at the country level, with revenue and market share for key countries in the world, from 2020 to 2025. and 3D-IC Packaging market forecast, by regions, by Type and by Application, with consumption value, from 2026 to 2031.

Chapter 11, market dynamics, drivers, restraints, trends, Porters Five Forces analysis.

Chapter 12, the key raw materials and key suppliers, and industry chain of 3D-IC Packaging.

Chapter 13, to describe 3D-IC Packaging research findings and conclusion.

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